

AMENDMENTS TO THE SPECIFICATION

On page 5, before the heading “Detailed Description of the Invention”, please insert the following heading and paragraph:

Brief Description of the Drawing

The Figure is a schematic view of an embodiment of the semiconductor element of the invention which has been encapsulated.

On page 5, please replace the second paragraph after the heading “Detailed Description of the Invention”, with the following amended paragraph:

As can be seen in the Figure, The the semiconductor device of the invention comprises a substrate (1) and a semiconductor element (2) mounted thereon through a bump bonding part (3), wherein the semiconductor element (2) has been encapsulated by coating the back (4) and the edges (5) of the semiconductor element (2) with a thermosetting sheet material (6) having tackiness.